

tentative

Туре	Ag <sup>*</sup> Aİ <sup>*</sup>	V <sub>DRM</sub> / V <sub>RRM</sub>	V <sub>DSM</sub> /V <sub>RSM</sub> [∀]	<i>I<sub>T(AV)</sub></i> [A]	Chip Size [mm] x [mm]	Package Options	• <del> </del>
CWP 52-	16 🗆 🗹	1600	1700	97	13.00 9.77	sawn on foil ✓ unsawn wafer ✓ in waffle pack ✓	
	*Frontside options					*Please contact IXYS chip sales	

## **Mechanical Parameters**

Area active Area total Wafer size Ø Thickness Material Max. possible chips per wafer Passivation front side Metallization top side top side Recom. wire bonds (AI) Cathode \* = Stitchbonds Number / Ø [µm] 12\* / 500 Metallization backside Reject Ink Dot Size Recom. Storage Environment sawn on foil unsawn wafer in waffle pack T<sub>stq</sub>

0.69 cm<sup>2</sup>
1.27 cm<sup>2</sup>
150 mm
380 μm
Si
110
Glassivation

bondable: Al
Cathode Gate

2\* / 500 1 / 500

solderable (only): Ti / Ni / Ag \*

solderable: Ti / Ni / Ag \*

Ø 0.4-1.0 mm

in org. container, in dry nitrogen < 6 month in org. container, in dry nitrogen < 2 year in org. container, in dry nitrogen < 2 year Tata -40 ... 40 °C

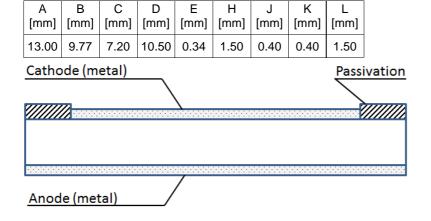
### **Features**

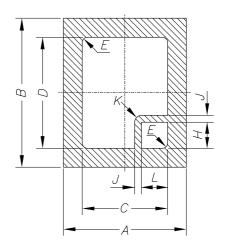
- planar passivated with guardring and channelstopper
- Planar front and back surface
- Non-structured anode contact on full area bottom side

### **Applications**

- DC motor control
- AC power control
- Softstart AC motor controller
- Light, heat and temperature control

# **Dimensions**





<sup>\*</sup>Sinterable top/bottom side on request

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	Ratings				
Symbol	Conditions	min.	typ.	max.	
I <sub>R</sub>	$V_D = Vr = Vrr$	$T_{VJ} = 25^{\circ}C$		0.1	m/
		$T_{V,I} = 150^{\circ}C$		20	m/
<b>ν</b> <sub>τ</sub>	$I_{T} = 200 \text{ A}$	$T_{VJ} = 25 ^{\circ}\text{C}$		1.38	١
		T <sub>v,i</sub> = 150 °C		1.40	\
$V_{\tau o}$	For power-loss	s calculations only		0.9	\
<b>r</b> 7	T <sub>v,j</sub> = 150 °C		Y	2.40	mΩ
<b>V</b> <sub>G7</sub>	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$		1.5	١
		$T_{VJ} = -40$ °C		1.6	\
I <sub>GT</sub>	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$ 27		95	mΑ
		$T_{VJ} = -40$ °C		200	mΑ
$V_{GD}$	$T_{VJ} = 150 ^{\circ}\text{C}$	$V = \frac{2}{3} V_{DRM}$		0.2	\
l <sub>gd</sub>				10	m/
I <sub>L</sub>	$t_{p} = 10 \ \mu s$	$T_{VJ} = 25^{\circ}C$ $I_{G} = 0.45 \text{ A}$ $di_{G}/dt = 0.45 \text{ A}/\mu\text{s}$		450	m/
I <sub>H</sub>	R <sub>GK</sub> = ∞	$T_{V,I} = 25^{\circ}C$ $V_D = 6 \text{ V}$		200	m/
t <sub>gd</sub>	$V_D = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25^{\circ}C$		2	μ
	$I_{G} = 0.5  A$	$di_{G}/dt = 0.5 A/\mu$			
t <sub>q</sub>	V <sub>R</sub> = 100 V	$I_{T} = 150 \text{ A}$ -di/dt = 10 A/ $\mu$ s	150		μ
	$t_p = 200  \mu s$	$dv/dt = 20 V/\mu s V_D = \frac{2}{3} V drm T_{V,J} = 150 °C$			
(di/dt) <sub>c</sub>	repetitive	$I_{\tau} = 150$ A		150	A/µs
	non repetitive	$I_{T} = 97$ A		500	A/µs
	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150 ^{\circ}\text{C}$ $di_{G}/dt = 0.45  \text{A/}\mu\text{s}$			
	$I_{G} = 0.45 \text{ A}$	$t_p = 200 \ \mu s$ $f = 50 \ Hz$			
(dv/dt) <sub>cr</sub>	· ·	$V_{DR} = \frac{2}{3} V_{DRM}$		1000	V/µs
	R <sub>GK</sub> = ∞	method 1 (linear voltage rise)			
$P_{\scriptscriptstyle GM}$	$T_{VJ} = 150  ^{\circ}\text{C}$	$t_p = 30 \mu\text{s}$		10	W
		$t_p = 3E \mu s$		5	W
P <sub>GAV</sub>				0.5	
V <sub>RGM</sub>				10	V
T <sub>VJ</sub>		-40		150	°C
I <sub>T(AV)</sub>	$T_C = 100 ^{\circ}C$	180° rect.		97	A
	T <sub>VJ</sub> = 150 °C	180° sine		tbd	A
I <sub>TSM</sub> *	$T_{VJ} = 45^{\circ}C$	t = 10 ms (50) Hz, sine		1500	A
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		1700	Α
	$T_{VJ} = 150  ^{\circ}\text{C}$	t = 10 ms (50) Hz, sine		1300	A
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		1380	Α
Pt *	$T_{VJ} = 45^{\circ}C$	t = 10 ms (50) Hz, sine		11250	As
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		11994	A s
	T <sub>VJ</sub> = 150 °C	t = 10 ms (50) Hz, sine		8450	A s
	$V_R = 0 V$	t = 8.3 ms (60) Hz, sine		7903	A s
R <sub>thJC</sub> *	DC current		0.38		K/W

<sup>\*</sup> Data according to assembled product tbd

Data according to IEC 60747

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- to perform joint risk and quality assessments;
- the conclusion of quality agreements;
- to establish joint measures to ensure application specific product capabilities and notify that IXYS may delivery dependent on the realization of any such measures.